TOSHIBA Field Effect Transistor Silicon P Channel MOS Type (U-MOS III)

# **TPC6105**

# Notebook PC Applications Portable Equipment Applications

- Low drain-source ON resistance: RDS (ON) =  $72 \text{ m}\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 4.7 \text{ S (typ.)}$
- Low leakage current:  $IDSS = -10 \mu A (max) (VDS = -20 V)$
- Enhancement mode:  $V_{th} = -0.5 \text{ to } -1.2 \text{ V}$

 $(V_{DS} = -10 \text{ V}, I_{D} = -200 \text{ }\mu\text{A})$ 

#### **Maximum Ratings (Ta = 25°C)**

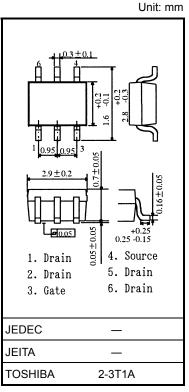
Characteristics			Symbol	Rating	Unit	
Drain-source voltage			$V_{DSS}$	-20	V	
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )			$V_{DGR}$	-20	V	
Gate-source voltage			V <sub>GSS</sub>	±8	V	
Drain current	DC	(Note 1)	I <sub>D</sub>	-2.7	А	
Diamicunent	Pulse	(Note 1)	$I_{DP}$	-10.8		
		(t = 5 s) (Note 2a)	$P_{D}$	2.2	W	
		(t = 5 s) (Note 2b)	$P_{D}$	0.7	W	
Single pulse avalanche energy (Note 3)			E <sub>AS</sub>	1.2	mJ	
Avalanche current			I <sub>AR</sub>	-1.35	Α	
Repetitive avalanche energy (Note 4)			E <sub>AR</sub>	0.22	mJ	
Channel temperature			T <sub>ch</sub>	150	°C	
Storage temperature range			T <sub>stg</sub>	-55~150	°C	

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	R <sub>th (ch-a)</sub>	56.8	°C/W
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	R <sub>th (ch-a)</sub>	178.5	°C/W

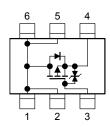
Note 1, Note 2, Note 3, Note 4 and Note 5: See the next page.

This transistor is an electrostatic-sensitive device. Please handle with caution.



Weight: 0.011 g (typ.)

#### **Circuit Configuration**



## Electrical Characteristics (Ta = 25°C)

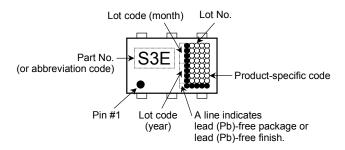
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cui	rrent	I <sub>GSS</sub>	$V_{GS} = \pm 8 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cut-off curr	ent	I <sub>DSS</sub>	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μА
Drain-source breakdown voltage		V (BR) DSS	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-20	_	_	V
Diaiii-souice bie	ardown voltage	V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 8 \text{ V}$	-12 — — 0.5 1.2			
Gate threshold v	oltage	V <sub>th</sub>	$V_{DS} = -10 \ V, \ I_D = -200 \ \mu A$	-0.5	_	-1.2	V
		R <sub>DS (ON)</sub>	$V_{GS} = -1.8 \text{ V}, I_D = -0.7 \text{ A}$	_	215	300	mΩ
Drain-source ON	resistance	R <sub>DS (ON)</sub>	$V_{GS} = -2.5 \text{ V}, I_D = -1.4 \text{ A}$	_	110	160	
		R <sub>DS (ON)</sub>	$V_{GS} = -4.5 \text{ V}, I_D = -1.4 \text{ A}$	_	72	110	
Forward transfer	rward transfer admittance		$V_{DS} = -10 \text{ V}, I_D = -1.4 \text{ A}$	2.4	4.7	_	S
Input capacitance		C <sub>iss</sub>		_	470	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	70	_	
Output capacitance		Coss		_	80	_	
Switching time	Rise time	t <sub>r</sub>	, 0 V ¬ Γ I <sub>D</sub> = −1.4 A	_	5	_	
	Turn-on time	t <sub>on</sub>	ACS -2 A ID = -1.4 W	_	9	_	ns
	Fall time	t <sub>f</sub>	4.7 \\ \frac{\text{4.7 \Omega}}{\text{3.7 \Omega}} \\ \frac{\text{9.7 \Omega}}{\text{9.7 \Omega}} \\ \text{8.1 \Delta 7.2 \Omega} \\ \text{8.2 \Delta 7.2 \Omega} \\ \text{8.2 \Delta 7.2 \Omega} \\ 8.2 \Delta 7.2 \Ome	_	8	_	
	Turn-off time	t <sub>off</sub>	$V_{DD} \simeq -10 \text{ V}$ Duty $\leqq$ 1%, $t_W = 10 \mu\text{s}$	_	26	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq -16 \text{ V}, V_{GS} = -5 \text{ V},$		6	_	
Gate-source charge		Q <sub>gs</sub>	$I_D = -2.7 \text{ A}$	_	4	_	nC
Gate-drain ("miller") charge		Q <sub>gd</sub>	]	_	2	_	

### Source-Drain Ratings and Characteristics (Ta = 25°C)

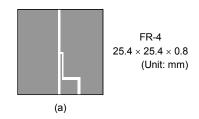
Charact	eristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	-	-	_	-10.8	Α
Forward voltage	(diode)	V <sub>DSF</sub>	$I_{DR} = -2.7 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V

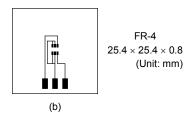
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#### Marking (Note 5)

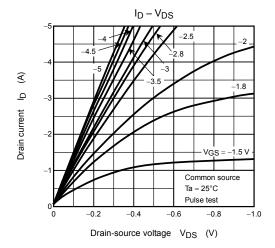


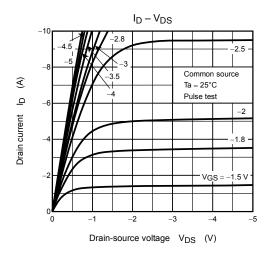
- Note 1: Ensure that the channel temperature does not exceed 150°C.
- Note 2: (a) Device mounted on a glass-epoxy board (a) (t = 5 s)
  - (b) Device mounted on a glass-epoxy board (b) (t = 5 s)

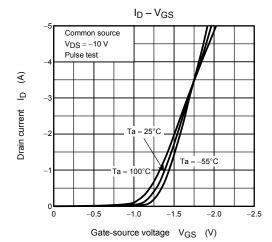


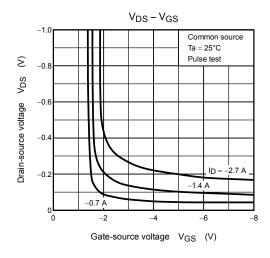


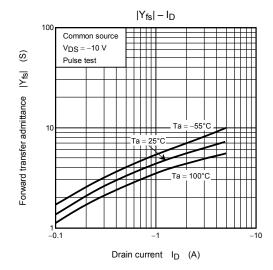
- Note 3:  $V_{DD} = -16 \text{ V}$ ,  $T_{ch} = 25^{\circ}\text{C}$  (initial), L = 0.5 mH,  $R_G = 25 \Omega$ ,  $I_{AR} = -1.35 A$
- Note 4: Repetitive rating: pulse width limited by maximum channel temperature
- Note 5: on the lower left of the marking indicates Pin 1.

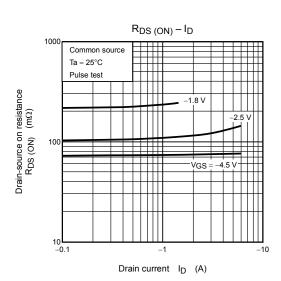


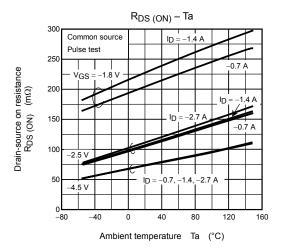


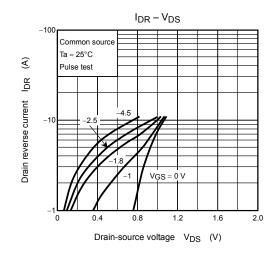


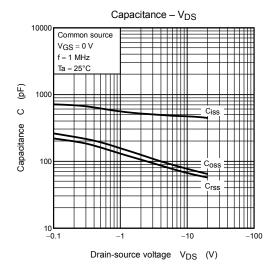


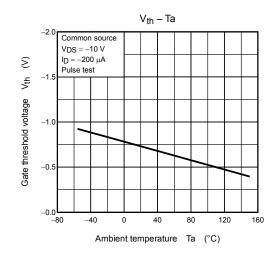


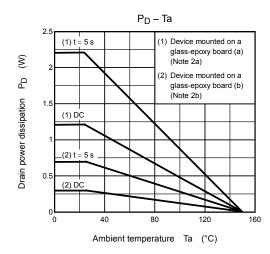


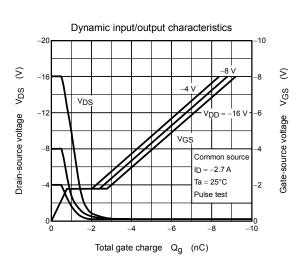




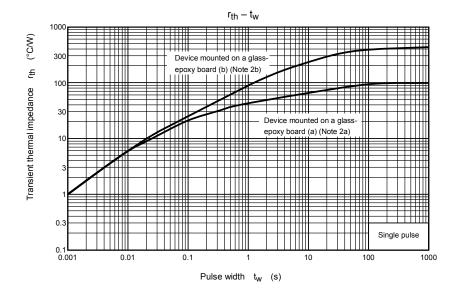


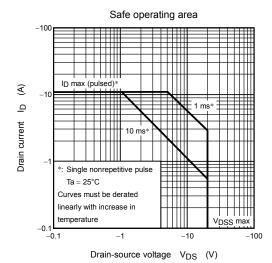






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